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Sub B1*

a first chamber containing the exposure apparatus therein;

a second chamber provided adjacent to the first chamber and which contains the substrate processing apparatus therein;

B' concluded

an environment sensor provided in at least one of the first and the second chambers which measures an environment [of at least one of the said exposure apparatus and said substrate processing apparatus] in said at least one of the first and the second chambers; and

a control device [which controls] electrically connected to the environment sensor, said control device controlling the environment [of at least one of said exposure apparatus and said substrate processing apparatus] in said at least one of the first and the second chambers on the basis of a measured value given from said environment sensor in such a manner that the environment [in] of said exposure apparatus becomes [substantially] the same as the environment in said substrate processing apparatus.

2. (Amended) A lithography system according to claim 1, wherein said environment sensor measures at least one of pressure, temperature and humidity in said [apparatus] at least one of the first and the second chambers.

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5. (Amended) A lithography method for controlling an environment in an exposure apparatus which [is adapted to expose] exposes a substrate and which is connected to a substrate

processing apparatus which processes the substrate before or after exposure, the method comprising the steps of:

obtaining data regarding the environment in a processing chamber in which said substrate processing apparatus is provided; and

controlling the environment in an exposure chamber in which said exposure apparatus is provided, on the basis of the obtained data.

7. (Amended) A method according to claim 5, wherein the environment in said exposure [apparatus] chamber is controlled to be [substantially] the same as the environment in said [substrate processing apparatus] processing chamber.

12. (Amended) A lithography method for controlling an environment in a substrate processing apparatus which [is adapted to process] processes a substrate before or after exposure [and which is] said processing apparatus being connected to an exposure apparatus which exposes the substrate before or after the processing, the method comprising the steps of:

obtaining data regarding the environment in an exposure chamber in which said exposure apparatus is provided; and

controlling the environment in a processing chamber in which said processing apparatus is provided, on the basis of the obtained data.

13. (Amended) [A processing apparatus] A method according to claim 12, wherein [it] the processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

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14. (Amended) [A processing apparatus] A method according to claim 12, wherein the environment in said substrate processing [apparatus] chamber is controlled to be [substantially] the same as the environment in said exposure [apparatus] chamber.

15. (Amended) [A processing apparatus] A method according to claim 12, wherein the data relates to at least one of air pressure, temperature and humidity.

20. (Amended) A method for making an exposure apparatus which [is adapted to expose] exposes a substrate, [and which is] said exposure apparatus being connected to a processing apparatus contained in a processing chamber which processes the substrate before or after exposure of the substrate, the method comprising the steps of:

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providing an exposure body in an exposure chamber different from the processing chamber, the exposure body performing an exposure operation of the substrate;

providing an adjusting device which adjusts an environment in said exposure [apparatus] chamber; and

providing a control device which controls said adjusting device on the basis of data regarding the environment in said [substrate processing apparatus] processing chamber.

23. (Amended) A method for making a substrate processing apparatus which [is adapted to process] processes a substrate and which is connected to an exposure apparatus contained in an exposure chamber which exposes the substrate before or after the processing of the substrate, the method comprising the steps of:

providing a processing body in a processing chamber different from the exposure chamber,
the processing body performing a processing operation to the substrate;

providing an adjusting device which adjusts an environment in said [substrate processing apparatus] processing chamber; and

providing a control device which controls said adjusting device on the basis of data regarding the environment in said [exposure apparatus] exposure chamber.

26. (Amended) A lithography method using an exposure apparatus which exposes a substrate and a substrate processing apparatus which processes the substrate before or after exposure, the method comprising the steps of:

obtaining data regarding an environment in one of an exposure chamber in which said exposure apparatus is contained and a processing chamber in which said substrate processing apparatus is contained; and

above, but fail to disclose an art of controlling a condition of the environment within the chambers 3 and 4.

The other independent claims 5, 12, 20, 23 and 26-28 all contain similar recitations.

Amended claim 5 recites, among other things, the recitations of "obtaining data regarding **the environment in a processing chamber** in which said substrate processing apparatus is provided;" and "**controlling the environment in an exposure chamber** in which said exposure apparatus is provided, on the basis of the obtained data."

Amended claim 12 recites, among other things, the recitations of "obtaining data regarding **the environment in an exposure chamber** in which said exposure apparatus is provided;" and "**controlling the environment in a processing chamber** in which said processing apparatus is provided, on the basis of the obtained data."

Amended claim 20 recites, among other things, the recitations of "providing an adjusting device which **adjusts an environment in said exposure chamber**;" and "providing a control device which controls said adjusting device on the basis of data regarding the environment in said processing chamber."

Amended claim 23 recites, among other things, the recitations of "providing an adjusting device which **adjusts an environment in said processing chamber**;" and "providing a control device which controls said adjusting device on the basis of data regarding the environment in said exposure chamber."